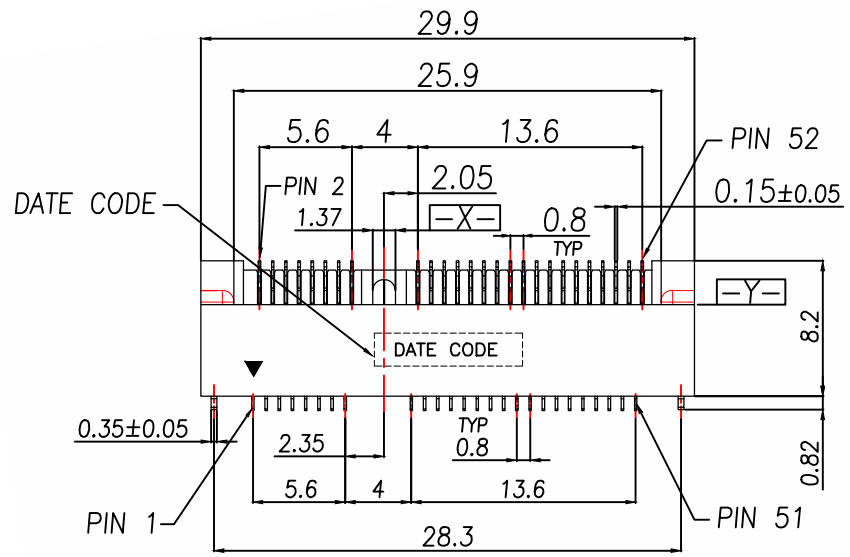


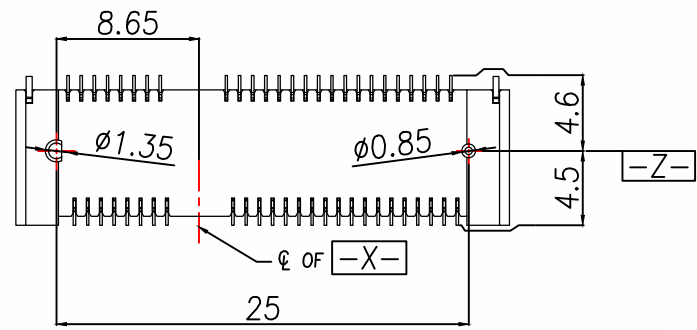
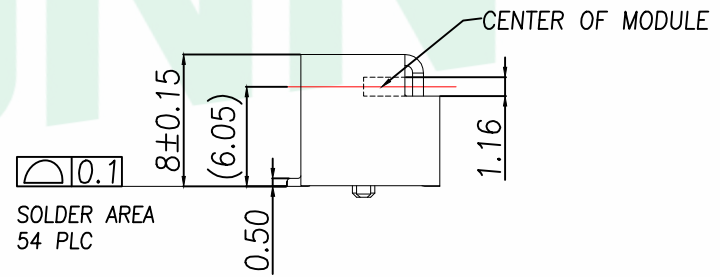
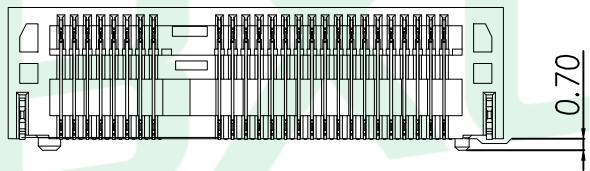
SCALE 0.6

REV.	DESCRIPTION	ECN NO.	NAME	DATE



NOTES:

- MATERIAL:
HOUSING: THERMOPLASTIC, HIGH TEMP, UL94V-0, BLACK COLOR,
CONTACTS: COPPER ALLOY.
PEGS: COPPER ALLOY.
- FINISH:
CONTACTS: SELECTED GOLD PLATING ON THE CONTACT AREA,
1u" MIN. GOLD PLATING ON THE SOLDERTAILS,
50 u" MIN. NICKEL UNDERPLATING OVER ALL.
PEGS: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.



GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD			
DIM.	TOL.	TITLE: 0.80MM PITCH MINPCIEXPRESS HIGH=8.0mm		
x.	±0.40	52 PIN CONNECTOR		
x.x	±0.30	DWG. NO.: PCIE-H8.0-P5236	CHECKED: MAX	
x.xx	±0.20	PART NO.: PCIE-H8.0-P5236	DRAWN: ELLA	
GENERAL ANGLE:		UNIT: mm	SCALE: none	SHEET: 1 of 1
x.	±1.5°	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL
x.x'	±1.0°			
x.xx'	±0.5°			

BXCONN[®]



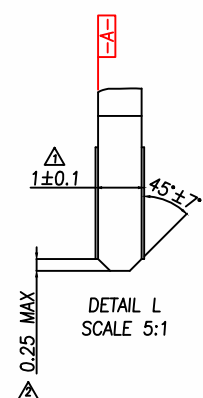
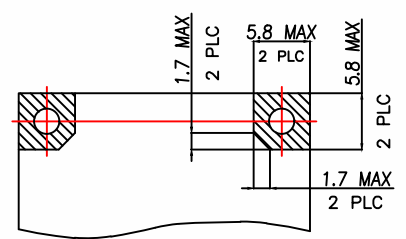
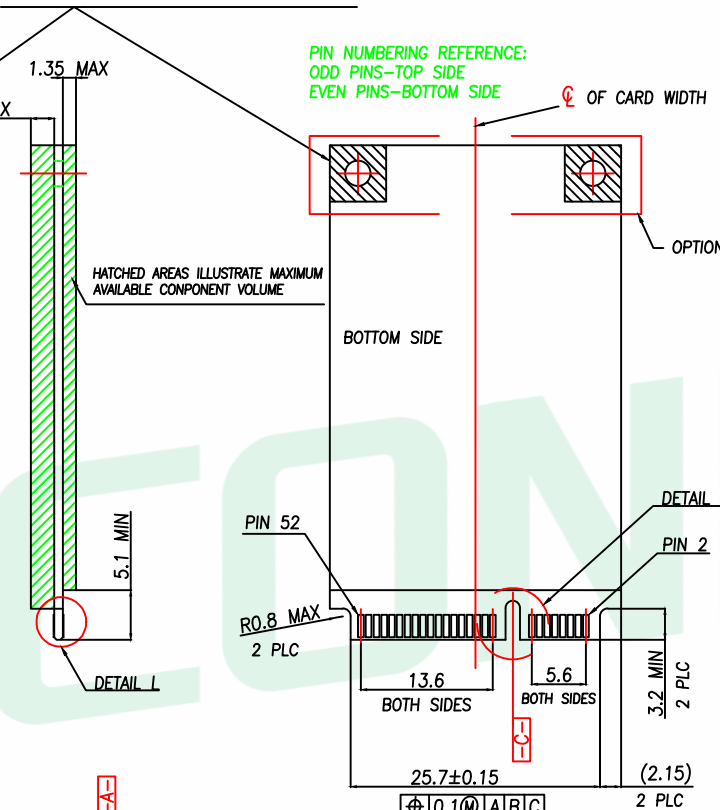
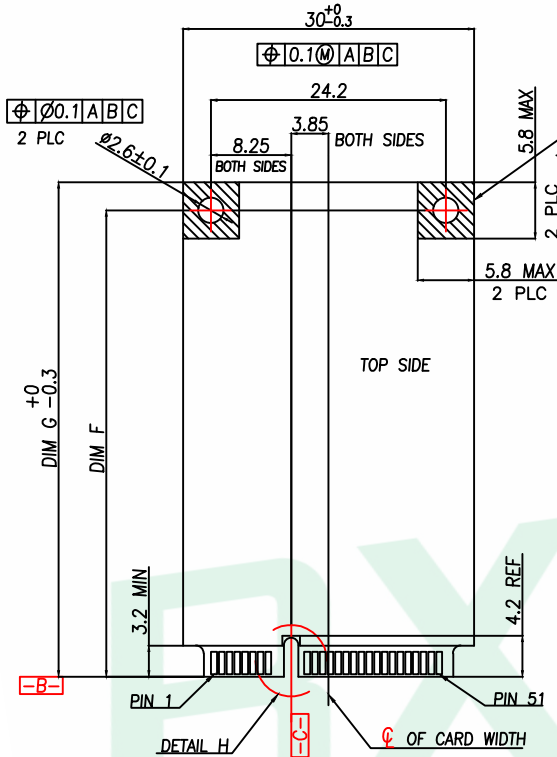
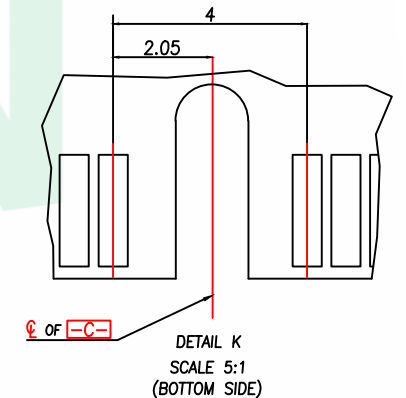
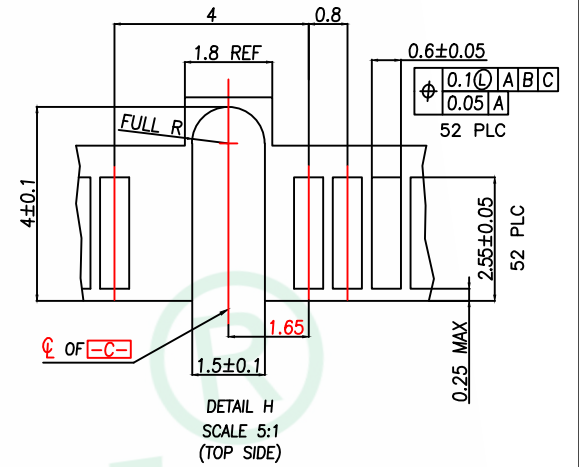
SCALE 0.6

REV.	DESCRIPTION	ECN NO.	NAME	DATE

COMPONENT AND ROUTING (ALL LAYERS) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS

DIM F	DIM G	
48.05	50.95	FULL-MINI CARD
23.9	26.8	HALF-MINI CARD

PIN NUMBERING REFERENCE:
ODD PINS-TOP SIDE
EVEN PINS-BOTTOM SIDE



- NOTES:
- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
 - △ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING BURRS FROM PCB AND CONTACT MATERIALS.

FOR PCI EXPRESS MINI CARD

GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD		
DIM. TOL.	TITLE: 0.80MM PITCH MINPCIEXPRESS HIGH=8.0mm 52 PIN CONNECTOR		
x. ±0.40	DWG. NO.: PCIE-H8.0-P5236		
x.x ±0.30	CHECKED: MAX		
x.xx ±0.20	DRAWN: ELLA		
GENERAL ANGLE:	PART NO.: PCIE-H8.0-P5236		
x. ±1.5°	DWG. NO.: PCIE-H8.0-P5236		
x.x ±1.0°	DWG. NO.: PCIE-H8.0-P5236		
x.xx ±0.5°	DWG. NO.: PCIE-H8.0-P5236		
UNIT: mm	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4
LAYER: bxconn		APPROVED: WILL	

